



Material Content Data Sheet



Sales Product Name		BTS721L1		Issued		20. July 2018		
MA#		MA001208538						
Package		PG-DSO-20-31		Weight*		499.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.030	2.81	2.81	28076	28076
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	non noble metal	iron	7439-89-6	3.388	0.68		6780	
wire	non noble metal	copper	7440-50-8	137.580	27.53	28.25	275315	282519
	noble metal	gold	7440-57-5	1.516	0.30	0.30	3033	3033
	encapsulation	organic material	carbon black	1333-86-4	0.668	0.13		1336
encapsulation	plastics	epoxy resin	-	30.709	6.15		61453	
	inorganic material	silicondioxide	60676-86-0	302.421	60.52	66.80	605182	667971
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5495	5495
plating	noble metal	silver	7440-22-4	3.187	0.64	0.64	6377	6377
glue	plastics	epoxy resin	-	0.571	0.11		1143	
	noble metal	silver	7440-22-4	2.692	0.54	0.65	5386	6529
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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